

Discription

The BV05C protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



SOD-323

Features

- ★ Ultra Low Capacitance 0.6 pF(Typ)
- ★ 300W peak pulse power (8/20uS)
- ★ Working Voltage 5V
- ★ Low leakage current nA Level
- ★ Complies with following standards
 - --IEC 61000-4-2(ESD) immunity test:

Air discharge: ±30KV

Contact discharge: ±30KV

--IEC61000-4-5 (Lightning) 10A (8/20uS)

★ RoHS compliant



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
BV05C	SOD-323	3000

Absolute Ratings (T_{amb}=25°C)

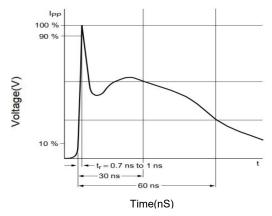
Symbol	Parameter		Value	Units
P _{PP}	Peak Pulse Power ($t_p = 8/20 \mu s$)		160	W
T _L	Maximum lead temperature for soldering during 10s		260	°C
T _{stg}	Storage Temperature Range		-55 to +155	°C
T _{op}	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air disc contact disc		±30 ±30	KV

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

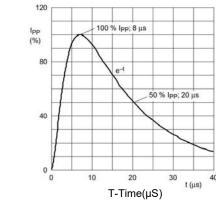
Device	V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	I _T	V _C (V) @ I _{PP} =10 A*	V _c (V) @ I _{PP} =10 A*	I _{PP} (A)*	P _{PK} (W)*	C (pF)
	Max	Max	Min	mA	Тур	Max	Max	Max	Тур
BV05C	5.0	0.1	6.1	1	14	16	10	160	0.6

PP-Peak Pulse Current-%of IPP

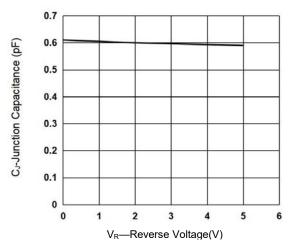
Typical Performance Characteristics (T_A=25°C unless otherwise Specified)



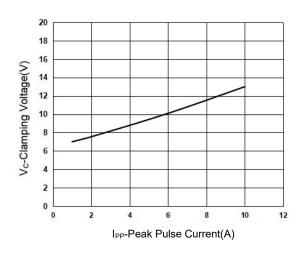
IEC61000-4-2 Pulse Waveform



IEC61000-4-5 8X20μs Pulse Waveform

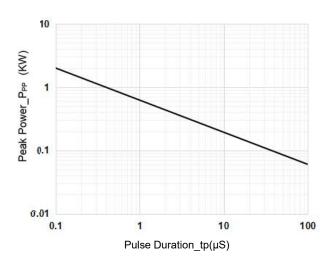


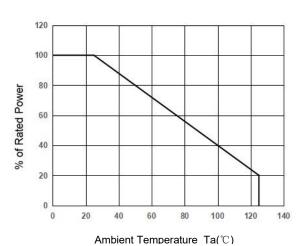
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current

^{*}Surge current waveform per Figure 1.



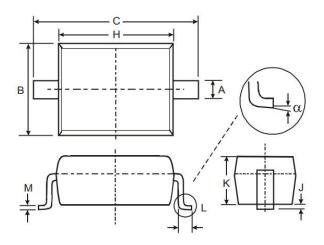


Peak Pulse Power vs. Pulse Time

Power Derating Curve

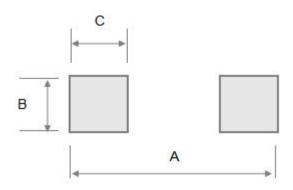
Package Outline Dimensions

SOD-323



Symbol	Dimensions		
Symbol	Min	Max	
А	0.25	0.40	
В	1.20	1.40	
С	2.35	2.75	
Н	1.50	1.80	
J	0.01	0.15	
K	0.75	1.05	
L	0.20	0.40	
М	0.08	0.25	
α	0°	8°	

Soldering Footprint (mm)



Symbol	Dimensions
Α	3.20
В	0.80
С	0.80



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